



## IC Snap Cure Oven

**Feature:**

- Fully automatic curing system for fast-cure glue.
- Easy to connect with kinds of Die-Bonder machines.
- Suitable for different type of packaging without change kits.
- Flexible for kinds of curing process.
- Dual language ( Chinese/English ) operation interface and Windows based on MMI, easy to operate.

**Application:**

- For Die-Bonding and curing process in-line purpose.
- For Die-Bonding process of package Stacking Dies.
- Pre-Heating/Post-Heating of Flip-Chip Under-Fill process.

## IC Snap Cure Oven

### Specifications

1	<b>Substrate Size</b>	120~260 (W) x 45~90 (D) mm
2	<b>UPH (Throughput)</b>	720 ea/hour (Curing Time: 3 sec + Index Time)
3	<b>Heating System</b>	PID Control Curing Stations
4	<b>Transfer Unit</b>	Wire / Strip Indexer
5	<b>Magazine Size</b>	Max. 270(W) x 90(D) x 160(H) mm
6	<b>Facilities</b>	220 VAC / 1Phase / 50 Hz, Air: 5 kgf/cm <sup>2</sup> (min.)
7	<b>Weight</b>	Approx. 650 kg
8	<b>Machine Dimensions</b>	1130(W) x 1270(D) x 1640(H) mm

### Ordering Information

<b>SC - 901 (M) - I</b>	For Strip/Lead-Frame, 4-Stainless Wire Indexer, 0~3mm Heating Height
<b>SC - 902 - I</b>	For Power IC Strip, 232(W) x 55(D) x 0.8(t)mm
<b>SC - 903 - I</b>	For Standard Boat Type, 260(W) x 75(D)x 0.8(t) mm
<b>SC - 904 - I</b>	For High Temperature Process (10 Curing Stations)
<b>SC - 901 - S</b>	Stand-Alone Type (Including Loader and Un-Loader)